

## XCede<sup>®</sup> HD2

## DESIGNED TO ACHIEVE 56G DATA RATE REQUIREMENTS WITH HIGHER DENSITY

While maintaining the same mating interfaces with XCede® HD and XCede® HD Plus, this connector provides developers with a readily available robust solution for tighter card pitches and chassis designs where space requirements and density are critical. These connectors are available in 3-, 4- and 6-Pair configurations.

- Differential pairs 28-84 per inch (11-33 differential pairs per centimeter)
- Modular construction with integrated power and guidance options
- Compliance with the hard metric form factor requirements outlined in EN 61076-4-101:2001
- 90Ω impedance



#### **FEATURES**

- Data rates scalable to 56Gb/s to support system upgrades without costly redesigns
- Compliance with the hard metric form factor requirements outlined in EN 61076-4-101:2001
- Proprietary crosstalk reducing technologies
- 15.7mil drill compliant pin allows deeper backdrilling
- Optimized footprints
- Shielded contacts mate before signal contacts, providing up to a 4mm minimum wipe
- Embedded capacitor available
- Differential pairs 28-84 per inch (11-33 differential pairs per centimeter)

#### **BENEFITS**

- Gear practical performance requirements for future data rates while making a significant impact on current systems
- Highest density with 1.80mm pitch
- Proven EMI and signal integrity advantages
- Improved impedance matching
- Complete solution for unique customer requirements
- Enables hot plugging
- Additional margin and overall system cost savings
- Meets high density application requirements

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## **TECHNICAL INFORMATION**

#### MATERIAL

- Contact Finish Area: Gold
- Contact Base Metal: High performance copper alloy
- Housings: Glass reinforced polyester (LCP)

#### **ELECTRICAL PERFORMANCE**

- Signal Contact Current Rating: 1A
- Contact Resistance Change:  $10m\Omega$  max.
- Dielectric Withstanding Voltage: 750V RMS peak

#### **MECHANICAL PERFORMANCE**

- 2mm & 3mm signal wipes available
- Housing Capture: 0.8mm X & 0.61mm Y
- Guide Capture: 2mm X & Y
- Durability: 250 mating cycles

#### **ENVIRONMENTAL**

• Operating Temperature Range: -40°C to 105°C

#### **APPROVALS AND CERTIFICATIONS**

■ UL94 V-0

#### **SPECIFICATIONS**

- TB-2343 XCede® HD2 General Product Specification
- TB-2237 XCede® HD Family Routing Guidelines
- TB-2245 XCede® HD Family Backplane Removal and Reinsertion Process
- TB-2252 XCede® HD Family Backplane Installation Process
- TB-2253 XCede® HD Family Daughtercard Wafer Removal and Replacement
- TB-2344 XCede<sup>®</sup> HD2 Connector Design Guidelines

#### PACKAGING

• PVC trays (ESD)

#### **TARGET MARKETS/APPLICATIONS**



Switches Routers Wireless Infrastructure



Servers Networked Storage Systems Supercomputers

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#### Disclaimer